Amendments to the claims:

Claim 1 (original): Apparatus for processing articles comprising

movable parts for processing said articles,

a plurality of microcontroller boards secured to said apparatus,

said microcontroller boards having a plurality of logic chips secured thereto,

sensors for monitoring operation of said apparatus and providing input information regarding a plurality of monitored conditions to said microcontroller boards,

said microcontroller boards being structured to process said input information and emitting responsive control signals to other said microcontroller boards and control portions of said apparatus, and

communication means for effecting communication (a) between said sensors and said microcontroller boards, (b) among said microcontroller boards and (c) between said microcontroller boards and control portions of said apparatus, whereby said microcontroller boards will through receipt and processing of said input information for a plurality of monitored conditions and communicating with other said microcontroller boards effect control of a plurality of monitored apparatus conditions.

Claim 2 (currently amended): The apparatus of claim 1 including

said microcontroller boards being structured to emit ~~having means for emitting~~ control signals responsive to receipt of information from said sensors.

Claim 3 (original): The apparatus of claim 2 including

said microcontroller boards being secured to a movable or stationary portion of apparatus or both.

Claim 4 (original): The apparatus of claim 1 wherein

said processing includes creating said articles from workpieces.

Claim 5 (original): The apparatus of claim 4 including

said microcontroller boards being embedded within said apparatus.

Claim 6 (currently amended): The apparatus of claim 1 including

said communication means being structured to effect ~~having means for effecting~~ communication within said microcontroller boards.

Claim 7 (currently amended): The apparatus of claim 6 including

said communication means <u>being structured to effect</u> ~~having means for effecting~~ communication with other portions of said apparatus.

Claim 8 (original): The apparatus of claim 1 including

said microcontroller boards being disposed within a container.

Claim 9 (original): The apparatus of claim 1 including

a container disposed within a recess in said apparatus,

said microcontroller boards being disposed within said container, and

a sealing material covering said microcontroller boards.

Claim 10 (original): The apparatus of claim 9 including

said sealing material being an epoxy which substantially completely covers said logic chips, whereby removal of said epoxy will at least partially destroy said logic chips.

Claim 11 (original): The apparatus of claim 1 including

a display unit for displaying information regarding said apparatus, and

said display unit being operatively associated with said communication means.

Claim 12 (original): The apparatus of claim 2 including

said communication means having a component which receives feedback from said sensors and delivers responsive signals to at least one said microcontroller board.

Claim 13 (original):. The apparatus of claim 12 including

said microcontroller boards being structured to deliver control signals to other portions of said apparatus to effect a change therein.

Claim 14 (original): The apparatus of claim 1 including

calibration means disposed exteriorly of said microcontroller boards for providing information to said communication means prior to initiating operation of said apparatus.

Claim 15 (original): The apparatus of claim 1 including

said logic chips being disposed on both surfaces of at least one said microcontroller board.

Claim 16 (original): The apparatus of claim 2 including

at least one container having at least one said microcontroller board disposed therein, and

said container disposed at least partially within a recess in said apparatus.

Claim 17 (original): The apparatus of claim 16 including a resinous material encapsulating each said microcontroller board.

Claim 18 (original): The apparatus of claim 16 including said containers having only one said microcontroller board therein.

Claim 19 (original): The apparatus of claim 16 including said containers having a plurality of said microcontroller boards therein.

Claim 20 (original): The apparatus of claim 16 including at least two said containers.

Claim 21 (original): The apparatus of claim 20 including at least some of said containers having a plurality of said microprocessor boards.

Claim 22(original): The apparatus of claim 17 including said resinous material being epoxy.

Claim 23 (original): The apparatus of claim 4 including said workpieces being metal sheet stock.

Claim 24 (original): The apparatus of claim 1 including said processing including handling of pre-formed articles.

Claim 25 (original): The apparatus of claim 1 including said processing including inspection of said articles.

Claim 26 (original): The apparatus of claim 1 including said processing includes packaging of said articles.

Claim 27 (original): The apparatus of claim 4 including said articles include at least one article selected from the group consisting of semi-fabricated products and fabricated products.

Claim 28 (original): The apparatus of claim 1 including a container having at least one said microcontroller board disposed therein, and at least one said sensor disposed within said container.

Claim 29 (original): The apparatus of claim 28 including a plurality of said microcontroller boards disposed within said container.

Claim 30 (original): The apparatus of claim 28 including said container secured to said apparatus.

Claim 31 (original): The apparatus of claim 28 including said container disposed within a recess within said apparatus.

Claim 32 (original): The apparatus of claim 1 including said apparatus being portable apparatus.

Claim 33 (original): The apparatus of claim 1 including a plurality of microprocessor modules each containing a plurality of said microcontroller boards and being operatively associated with at least some said sensors and at least a portion of said communication means.

Claim 34 (original): The apparatus of claim 33 including said microprocessor modules being secured to different portions of said apparatus and at least some of them being structured to perform different functions than others of said microprocessor boards.

A 2 cancel

Claims 35-64 (cancelled).